

MPW #	Geometry	Reservation Close Date*	CDRS Submit Date@	Cancellation Deadline	Dry Run DRC CutOff	Other Participants Tapeout Date #&	Customer Tapeout Date#	Projected 1st Batch Bare Die Ship\$	Projected 2nd Batch Bare Die Ship\$	Process Offering
MPW18H0	0.18um	10/10/2022	10/17/2022	11/7/2022	11/21/2022	11/21/2022	12/5/2022	Early Feb 2023-End Feb 2023	Mid Mar 2023-Mid Mar 2023	Fab35_IC/BCDlite/UHV-HV18/MCU
MPW1434	12nm	10/6/2022	10/13/2022	11/3/2022	11/17/2022	11/17/2022	12/1/2022	End Mar 2023-Early Apr 2023	Early May 2023-Mid May 2023	12LP/12LP+
MPW4R12	45RFSOI_45nm	9/28/2022		10/26/2022	11/9/2022	11/9/2022	11/23/2022	End Mar 2023-Early Apr 2023	End Mar 2023-Early Apr 2023	45RF
MPW0472	40nm	9/26/2022	10/3/2022	10/24/2022	11/7/2022	11/7/2022	11/21/2022	End Feb 2022-Early Mar 2022	Mid Apr 2022-Mid Apr 2022	40LP/40RF/40LP-ESF3H/40RF_mmW
MPW4C06	45SPCLO_45nm	9/21/2022	9/28/2022	10/19/2022	11/2/2022	11/2/2022	11/16/2022	End May 2023-Early Jun 2023	Early Jul 2023-Mid Jul 2023	45SPCLO
MPW06B0	55nm	9/19/2022	9/26/2022	10/17/2022	10/31/2022	10/31/2022	11/14/2022	End Jan 2023-Early Feb 2023	End Mar 2023-Early Apr 2023	NVM/BCDL_ESF3L/BCDL(5/12/20V)/BCDL(30V)/BCDL_MTP/NVM_ULP
MPW9H16	9HP_90nm	9/14/2022		10/12/2022	10/26/2022	10/26/2022	11/9/2022	Mid Mar 2023-End Mar 2023	Mid Mar 2023-End Mar 2023	9HP
MPW2249	22nm	9/12/2022	9/19/2022	10/10/2022	10/24/2022	10/24/2022	11/7/2022	Early Jan 2023-Mid Jan 2023	Mid Jan 2023-Early Feb 2023	22FDX+/22FDX/22FDX-ATV/22eMRAM. Projected ship dates are NOT for eMRAM & ATV
								Early Jan	Mid Mar	

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MPW13C2	0.11/0.13um	9/5/2022	9/12/2022	10/3/2022	10/17/2022	10/17/2022	10/31/2022	2023-Early Jan 2023	2023-Mid Mar 2023	RFSOI-Gen2/BCDlite-Gen2/BCDL-Gen2-ATV125
MPW8X11	8XP_0.13um	8/31/2022		9/28/2022	10/12/2022	10/12/2022	10/26/2022	End Feb 2023-Early Mar 2023	End Feb 2023-Early Mar 2023	8XP
MPW4E03	45RFE_45nm	8/24/2022	8/31/2022	9/21/2022	10/5/2022	10/5/2022	10/19/2022	Early Mar 2023-Mid Mar 2023	Mid Apr 2023-End Apr 2023	45RFE
MPW5P05	5PA4_0.35um	8/17/2022		9/14/2022	9/28/2022	9/28/2022	10/12/2022	End Jan 2023-Early Feb 2023	End Jan 2023-Early Feb 2023	5PA4
MPW0368	28nm	8/15/2022	8/22/2022	9/12/2022	9/26/2022	9/26/2022	10/10/2022	End Dec 2022-Early Jan 2023	Mid Jan 2023-Early Feb 2023	28SLP/28SLPe/28SLP-RF/28SLP-HV/28SLP-ESF3
MPW8N06	130NSX1_0.13um	7/20/2022		8/17/2022	8/31/2022	8/31/2022	9/14/2022	End Dec 2022-Early Jan 2023	End Dec 2022-Early Jan 2023	130NSX1
MPW1433	12nm	7/20/2022	7/27/2022	8/17/2022	8/31/2022	8/31/2022	9/14/2022	End Dec 2022-Early Jan 2023	Early Feb 2023-Mid Feb 2023	12LP/12LP+
MPW18G9	0.18um	7/18/2022	7/25/2022	8/15/2022	8/29/2022	8/29/2022	9/12/2022	Mid Nov 2022-End Nov 2022	End Dec 2022-End Dec 2022	Fab35_IC/BCDlite/UHV-HV18/MCU
MPW2248	22nm	7/11/2022	7/18/2022	8/8/2022	8/22/2022	8/22/2022	9/5/2022	Early Nov 2022-Mid Nov 2022	Mid Nov 2022-Early Dec 2022	22FDX+/22FDX/22FDX-ATV/22eMRAM. Projected ship dates are NOT for eMRAM & ATV
MPW06A9	55nm	6/27/2022	7/4/2022	7/25/2022	8/8/2022	8/8/2022	8/22/2022	Early Nov 2022-Mid Nov 2022	Early Jan 2023-Mid Jan 2023	LPE/LPE-RF/LPX/HV(AMOLED)/BCDL(5/12/20V)/BCDL(30V)/BCDL_MTP/LPX_ULP
MPW4C05	45SPCLO_45nm	6/22/2022	6/29/2022	7/20/2022	8/3/2022	8/3/2022	8/17/2022	End Feb 2023-Early Mar 2023	Early Apr 2023-Mid Apr 2023	45SPCLO
								End Oct	End Dec	

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MPW13C1	0.11/0.13um	6/20/2022	6/27/2022	7/18/2022	8/1/2022	8/1/2022	8/15/2022	2022-End Oct 2022	2022-End Dec 2022	RFSOI-Gen1/BCDlite-Gen1/BCD-Gen1/G/LP/EEPROM/110TS
MPW9H15	9HP_90nm	6/15/2022		7/13/2022	7/27/2022	7/27/2022	8/10/2022	End Dec 2022-Early Jan 2023	End Dec 2022-Early Jan 2023	9HP
MPW8X10	8XP_0.13um	6/1/2022		6/29/2022	7/13/2022	7/13/2022	7/27/2022	End Nov 2022-Early Dec 2022	End Nov 2022-Early Dec 2022	8XP
MPW0471	40nm	5/30/2022	6/6/2022	6/27/2022	7/11/2022	7/11/2022	7/25/2022	End Oct 2022-Early Nov 2022	Mid Dec 2022-Mid Dec 2022	40LP/40RF/40RF_mmW
MPW4R11	45RFSOI_45nm	5/25/2022		6/22/2022	7/6/2022	7/6/2022	7/20/2022	End Nov 2022-Early Dec 2022	End Nov 2022-Early Dec 2022	45RF
MPW1514	0.15um	5/23/2022	5/30/2022	6/20/2022	7/4/2022	7/4/2022	7/18/2022	End Sept 2022-End Sept 2022	Mid Oct 2022-Mid Oct 2022	F3_150NM_MCU
MPW0367	28nm	5/16/2022	5/23/2022	6/13/2022	6/27/2022	6/27/2022	7/11/2022	Mid Sept 2022-Early Oct 2022	Mid Oct 2022-Early Nov 2022	28SLP/28SLPe/28SLP-RF/28SLP-HV/28SLP-ESF3
MPW2247	22nm	5/10/2022	5/16/2022	6/6/2022	6/20/2022	6/20/2022	7/4/2022	Early Sept 2022-Mid Sept 2022	Mid Sept 2022-Early Oct 2022	22FDX+/22FDX/22FDX-ATV/22eMRAM. Projected ship dates are NOT for eMRAM & ATV
MPW4E02	45RFE_45nm	4/27/2022	5/4/2022	5/25/2022	6/8/2022	6/8/2022	6/22/2022	End Sept 2022-Early Oct 2022	End Oct 2022-Early Nov 2022	45RFE
MPW5P04	5PA4_0.35um	4/20/2022		5/18/2022	6/1/2022	6/1/2022	6/15/2022	End Sept 2022-Early Oct 2022	End Sept 2022-Early Oct 2022	5PA4
MPW1432	12nm	4/20/2022	4/27/2022	5/18/2022	6/1/2022	6/1/2022	6/15/2022	End Sept 2022-Early Oct 2022	End Oct 2022-Early Nov 2022	12LP/12LP+

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MPW18G8	0.18um	4/18/2022	4/25/2022	5/16/2022	5/30/2022	5/30/2022	6/13/2022	Early Sept 2022-Mid Sept 2022	Mid Oct 2022-Mid Oct 2022	Fab35_IC/BCDlite/UHV-HV18/MCU
MPW06A8	55nm	4/4/2022	4/11/2022	5/2/2022	5/16/2022	5/16/2022	5/30/2022	Mid Aug 2022-Mid Aug 2022	Mid Oct 2022-Mid Oct 2022	NVM/BCDL_ESF3L/BCDL(5/12/20V)/BCDL(30V)/BCDL_MTP/NVM_ULP
MPW13C0	0.11/0.13um	3/28/2022	4/4/2022	4/25/2022	5/9/2022	5/9/2022	5/23/2022	End Jul 2022-End Jul 2022	End Sept 2022-Early Oct 2022	RFSOI-Gen2/BCDlite-Gen2
MPW8N05	130NSX1_0.13um	3/23/2022		4/20/2022	5/4/2022	5/4/2022	5/18/2022	End Aug 2022-Early Sept 2022	End Aug 2022-Early Sept 2022	130NSX1
MPW4C04	45SPCLO_45nm	3/23/2022	3/30/2022	4/20/2022	5/4/2022	5/4/2022	5/18/2022	End Oct 2022-Early Nov 2022	Early Jan 2023-Mid Jan 2023	45SPCLO
MPW9H14	9HP_90nm	3/16/2022		4/13/2022	4/27/2022	4/27/2022	5/11/2022	End Sept 2022-Early Oct 2022	End Sept 2022-Early Oct 2022	9HP
MPW2246	22nm	3/14/2022	3/21/2022	4/11/2022	4/25/2022	4/25/2022	5/9/2022	Mid Jul 2022-End Jul 2022	Mid Jul 2022-Early Aug 2022	22FDX+/22FDX/22FDX-ATV/22eMRAM. Projected ship dates are NOT for eMRAM & ATV
MPW8X09	8XP_0.13um	3/2/2022		3/30/2022	4/13/2022	4/13/2022	4/27/2022	End Aug 2022-Early Sept 2022	End Aug 2022-Early Sept 2022	8XP
MPW0470	40nm	2/21/2022	2/28/2022	3/21/2022	4/4/2022	4/4/2022	4/18/2022	Mid Jul 2022-End Jul 2022	Early Sept 2022-Mid Sept 2022	40LP/40RF/40LP-ESF3H/40RF_mmW
								End Jun	Early Aug	

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MPW1431	12nm	1/19/2022	1/26/2022	2/16/2022	3/2/2022	3/2/2022	3/16/2022	2022-Early Jul 2022	2022-Mid Aug 2022	12LP/12LP+
MPW2245	22nm	1/17/2022	1/24/2022	2/14/2022	2/28/2022	2/28/2022	3/14/2022	Mid May 2022-End May 2022	Early Jun 2022-Mid Jun 2022	22FDX+/22FDX/22FDX-ATV. Projected ship dates are NOT applicable for ATV.
MPW4R10	45RFSOI_45nm	1/12/2022		2/9/2022	2/23/2022	2/23/2022	3/9/2022	Early Jul 2022-Mid Jul 2022	Early Jul 2022-Mid Jul 2022	45RF
MPW18G7	0.18um	1/10/2022	1/17/2022	2/7/2022	2/21/2022	2/21/2022	3/7/2022	End May 2022-Mid Jun 2022	Early Jul 2022-Early Jul 2022	Fab35_IC/BCDlite/UHV-HV18/MCU
MPW06A7	55nm	12/27/2021	1/3/2022	1/24/2022	2/7/2022	2/7/2022	2/21/2022	Early May 2022-Mid May 2022	Early Jul 2022-Mid Jul 2022	HV(AMOLED)/BCDL(5/12/20V)/BCDL(30V)/BCDL_MTP
MPW4C03	45SPCLO_45nm	12/22/2021	12/29/2021	1/19/2022	2/2/2022	2/2/2022	2/16/2022	End Aug 2022-Early Sept 2022	Early Oct 2022-Mid Oct 2022	45SPCLO
MPW13B9	0.11/0.13um	12/20/2021	12/27/2021	1/17/2022	1/31/2022	1/31/2022	2/14/2022	End Apr 2024-End Apr 2024	End Jun 2022-End Jun 2022	RFSOI-Gen1/BCDlite-Gen1/BCD-Gen1/G/LP/EEPROM/110TS
MPW5P03	5PA4_0.35um	12/15/2021		1/12/2022	1/26/2022	1/26/2022	2/9/2022	Mid May 2022-End May 2022	Mid May 2022-End May 2022	5PA4
MPW9H13	9HP_90nm	12/15/2021		1/12/2022	1/26/2022	1/26/2022	2/9/2022	End Jun 2022-Early Jul 2022	End Jun 2022-Early Jul 2022	9HP
MPW0366	28nm	12/13/2021	12/20/2021	1/10/2022	1/24/2022	1/24/2022	2/7/2022	Mid Apr 2022-Early May 2022	Mid May 2022-Early Jun 2022	28SLP/28SLPe/28SLP-RF/28SLP-HV/28SLP-ESF3
MPW8X08	8XP_0.13um	12/1/2021		12/29/2021	1/12/2022	1/12/2022	1/26/2022	End May 2022-Early Jun 2022	End May 2022-Early Jun 2022	8XP
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MPW4E01	45RFE_45nm	11/24/2021	12/1/2021	12/22/2021	1/5/2022	1/5/2022	1/19/2022	2022-End May 2022	2022-End Jul 2022	45RFE
MPW2244	22nm	11/22/2021	11/29/2021	12/20/2021	1/3/2022	1/3/2022	1/17/2022	Mid Mar 2022-Early Apr 2022	Early Apr 2022-Mid May 2022	22FDX+/22FDX/22FDX-ATV/22eMRAM. Projected ship dates are NOT for eMRAM & ATV
MPW8N04	130NSX1_0.13um	11/17/2021		12/15/2021	12/29/2021	12/29/2021	1/12/2022	End Apr 2022-Early May 2022	End Apr 2022-Early May 2022	130NSX1
MPW1513	0.15um	11/15/2021	11/22/2021	12/13/2021	12/27/2021	12/27/2021	1/10/2022	Early Apr 2022-Early Apr 2022	Early May 2022-Early May 2022	F3_150NM_MCU
MPW18G6	0.18um	10/11/2021	10/18/2021	11/8/2021	11/22/2021	11/22/2021	12/6/2021	End Feb 2022-Mid Mar 2022	Early Apr 2022-Early Apr 2022	Fab35_IC/BCDlite/UHV-HV18/MCU
MPW1430	12nm	10/6/2021	10/13/2021	11/3/2021	11/17/2021	11/17/2021	12/1/2021	End Mar 2022-Early Apr 2022	Early May 2022-Mid May 2022	12LP
MPW2243	22nm	9/27/2021	10/4/2021	10/25/2021	11/8/2021	11/8/2021	11/22/2021	Mid Jan 2022-Early Feb 2022	Early Feb 2022-End Feb 2022	22FDX+/22FDX/22FDX-ATV/22eMRAM. Projected ship dates are NOT for eMRAM & ATV
MPW8N03	130NSX1_0.13um	9/22/2021		10/20/2021	11/3/2021	11/3/2021	11/17/2021	End Mar 2022-Early Apr 2022	End Mar 2022-Early Apr 2022	130NSX1
MPW06A6	55nm	9/21/2021	9/28/2021	10/19/2021	11/2/2021	11/2/2021	11/15/2021	End Jan 2022-Early Feb 2022	End Mar 2022-Early Apr 2022	55LPX/55LPe/55ULP/55BCDL/55NVM
MPW4R09	45RFSOI_45nm	9/19/2021		10/13/2021	10/27/2021	10/27/2021	11/10/2021	Mid Mar 2022-End Mar 2022	Mid Mar 2022-End Mar 2022	45RF

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MPW0469	40nm	9/13/2021	9/20/2021	10/11/2021	10/25/2021	10/25/2021	11/8/2021	End Jan 2022-End Jan 2022	End Mar 2022-End Mar 2022	40LP/40LP-ESF3/40RF
MPW9H12	9HP_90nm	9/11/2021		10/6/2021	10/20/2021	10/20/2021	11/3/2021	Mid Mar 2022-End Mar 2022	Mid Mar 2022-End Mar 2022	9HP
MPW5P02	5PA4_0.35um	9/10/2021		9/15/2021	9/29/2021	9/29/2021	10/13/2021	Mid Jan 2022-End Jan 2022	Mid Jan 2022-End Jan 2022	5PA4
MPW8X07	8XP_0.13um	9/8/2021		9/22/2021	10/6/2021	10/6/2021	10/20/2021	Early Mar 2022-Mid Mar 2022	Early Mar 2022-Mid Mar 2022	8XP
MPW1429	12nm	8/26/2021	8/12/2021	8/26/2021	9/1/2021	9/1/2021	9/15/2021	End Dec 2021-Early Jan 2022	Early Feb 2022-Mid Feb 2022	12LP
MPW4C02	45SPCLO_45nm	8/18/2021	8/25/2021	9/15/2021	9/29/2021	9/29/2021	10/13/2021	Mid Apr 2022-End Apr 2022	Early Jun 2022-Mid Jun 2022	45SPCLO
MPW0365	28nm	8/17/2021	8/23/2021	9/13/2021	9/27/2021	9/27/2021	10/11/2021	Mid Dec 2021-End Dec 2021	Early Jan 2022-Mid Jan 2022	28SLP/28SLPe/28SLP-RF/28SLP-HV/28SLP-ESF3
MPW13B8	0.11/0.13um	8/16/2021	8/23/2021	9/13/2021	9/27/2021	9/27/2021	10/11/2021	Early Dec 2021-Mid Dec 2021	Early Feb 2022-Early Feb 2022	RFSOI/G/LP/EEPROM/110TS/BCDlite/BCD
MPW1512	0.15um	8/9/2021	8/16/2021	9/6/2021	9/20/2021	9/20/2021	10/4/2021	Mid Dec 2021-Mid Dec 2021	Early Jan 2022-Early Jan 2022	F3_150NM_MCU
MPW2242	22nm	7/26/2021	8/2/2021	8/23/2021	9/6/2021	9/6/2021	9/20/2021	Mid Nov 2021-End Nov	Early Dec 2021-Mid Dec	22FDX+/22FDX/22FDX-ATV/22eMRAM. Projected

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								2021	2021	ship dates are NOT for eMRAM & ATV
MPW18G5	0.18um	7/26/2021	8/2/2021	8/23/2021	9/6/2021	9/6/2021	9/20/2021	End Nov 2021-Early Dec 2021	Early Jan 2022-Early Jan 2022	Fab35_IC/BCDlite/UHV-HV18/MCU
MPW06A4	55nm	7/19/2021	7/26/2021	8/16/2021	8/30/2021	8/30/2021	9/13/2021	End Nov 2021-Early Dec 2021	End Jan 2022-End Jan 2022	55LPX/55LPe/55ULP/55BCDL/55HV
MPW9H11	9HP_90nm	6/30/2021		7/28/2021	8/11/2021	8/11/2021	8/25/2021	Early Jan 2022-Mid Jan 2022	Early Jan 2022-Mid Jan 2022	9HP
MPW13B7	0.11/0.13um	6/28/2021	7/5/2021	7/26/2021	8/9/2021	8/9/2021	8/23/2021	End Oct 2021-End Oct 2021	End Dec 2021-End Dec 2021	RFSOI/BCDlite/BCD/LP
MPW0468	40nm	6/21/2021	6/28/2021	7/19/2021	8/2/2021	8/2/2021	8/16/2021	Early Nov 2021-Early Nov 2021	Early Jan 2022-Early Jan 2022	40LP/40LP-ESF3/40RF
MPW0364	28nm	6/16/2021	5/24/2021	6/14/2021	6/28/2021	6/28/2021	7/12/2021	Mid Sept 2021-End Sept 2021	End Sept 2021-Early Oct 2021	28SLP/28SLPe/28SLP-RF/28SLP-HV/28SLP-ESF3
MPW8X06	8XP_0.13um	6/10/2021		6/30/2021	7/14/2021	7/14/2021	7/28/2021	Early Dec 2021-Mid Dec 2021	Early Dec 2021-Mid Dec 2021	8XP
MPW06A3	55nm	5/31/2021	6/7/2021	6/28/2021	7/12/2021	7/12/2021	7/26/2021	Early Oct 2021-Mid Oct 2021	Early Dec 2021-Mid Dec 2021	55LPX/55LPe/55ULP/55BCDL/55NVM
MPW1428	12nm	5/29/2021	5/29/2021	5/29/2021	6/2/2021	6/2/2021	6/16/2021	End Sept 2021-Early Oct 2021	End Oct 2021-Early Nov 2021	12LP
MPW4C01	45SPCLO_45nm	5/28/2021	6/4/2021	6/25/2021	7/9/2021	7/9/2021	7/23/2021	End Nov 2021-Early Dec 2021	Early Jan 2022-Mid Jan 2022	45SPCLO
MPW2241	22nm	5/24/2021	5/31/2021	6/21/2021	7/5/2021	7/5/2021	7/19/2021	Mid Sept 2021-End Sept	Early Oct 2021-Mid Oct	22FDX+/22FDX/22FDX-ATV. Projected ship dates are

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								2021	2021	NOT applicable for ATV.
MPW4R08	45RFSOI_45nm	5/19/2021		6/16/2021	6/30/2021	6/30/2021	7/14/2021	Mid Nov 2021-End Nov 2021	Mid Nov 2021-End Nov 2021	45RF
MPW8S03	8SW_0.13um	5/4/2021		6/1/2021	6/15/2021	6/15/2021	6/29/2021	End Oct 2021-End Oct 2021	End Oct 2021-End Oct 2021	8SW
MPW18G4	0.18um	4/26/2021	5/3/2021	5/24/2021	6/7/2021	6/7/2021	6/21/2021	End Aug 2021-End Sept 2021	Early Oct 2021-Early Oct 2021	Fab35_IC/BCDlite/UHV-HV18/MCU
MPW13B6	0.11/0.13um	4/19/2021	4/26/2021	5/17/2021	5/31/2021	5/31/2021	6/14/2021	Mid Sept 2021-End Sept 2021	Mid Nov 2021-End Nov 2021	RFSOI/G/LP/EEPROM/110TS/BCDlite/BCD
MPW4C00	45SPCLO_45nm	4/16/2021	4/16/2021	4/16/2021	4/16/2021	4/16/2021	4/16/2021	End Aug 2021-Early Sept 2021	Early Oct 2021-Mid Oct 2021	45SPCLO
MPW06A2	55nm	4/5/2021	4/12/2021	5/3/2021	5/17/2021	5/17/2021	5/31/2021	Mid Aug 2021-Mid Aug 2021	Mid Oct 2021-Mid Oct 2021	55LPX/55LPe/55ULP/55BCDL/55HV
MPW9H10	9HP_90nm	3/31/2021		4/28/2021	5/12/2021	5/12/2021	5/26/2021	Early Oct 2021-Mid Oct 2021	Early Oct 2021-Mid Oct 2021	9HP
MPW9W07	9WG_90nm	3/17/2021		4/14/2021	4/28/2021	4/28/2021	5/12/2021	Mid Sept 2021-Early Oct 2021	Mid Nov 2021-End Nov 2021	9WG
MPW069A	55nm	6/5/2020	6/12/2020	7/3/2020	7/17/2020	7/17/2020	7/31/2020	Mid Oct 2021-End Oct 2021	Mid Dec 2021-End Dec 2021	55LPX/55LPe/55ULP/55BCDL/55DDI

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